

[Title of the Invention]

WINDING STRUCTURE OF BONDING WIRE FOR SEMICONDUCTOR DEVICES

[Document Name] ABSTRACT

[Problem]

An object of the present invention is to provide a novel winding structure of a bonding wire, the wire structure having a fastening force stronger than before, which does not collapse due to vibration, etc., during transportation. Another object of the present invention is to provide a winding structure of a bonding wire, the wire structure saving waste of wire and allowing smooth spool replacement operation.

[Structure]

The winding structure of the bonding wire of the present invention is a winding structure of a bonding wire wound on a spool comprising a lead winding part in which the wire is regularly wound, a main winding part in which the wire is cross-wound in multilayers, and a tail winding part in which the wire is regularly wound; wherein

at least one of oblique sides of both end shapes of the main winding part has a protruding portion of an intermediate oblique side or an upper oblique side, the intermediate oblique side having an elevation angle steeper than the elevation angle of a lower oblique side extending from the end of the spool;

the protruding portion is continued to a wave-like zigzag layer; and

the height of the peak of the upper oblique side is higher than the average height of the zigzag layer.

[Selected Drawing] Fig. 2